ABSTRACT OF THE DISCLOSURE

A crack-resistant compound suitable for use in semiconductor packaging applications such as package molding or integrated circuit die attachment. The compound may comprise an epoxy resin along with a relatively high percentage weight of anhydrous cement as an active filler. The compound exhibits the desirable properties of high strength at reflow temperatures, strong adhesion and thermal match to an integrated circuit die, die-attach pad and leadframe, and reduced moisture absorption. As such, the compound substantially reduce the incidence of "pop-corn" cracking in plastic surface mounts and other types of semiconductor device packages. The compound may be utilized to form a package body for a packaged semiconductor device, as an adhesive for attaching an integrated circuit die to an attach pad or other substrate in a semiconductor device package, as an underfill for solder joint protection, and in numerous other packaging applications.

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